SSN08LF BOM-style material declaration. BI Technologies Corporation **1/24/2011**

No content banned per EU RoHS. Average mass of SSN08LF thin film network is 0.08 grams each. Prepared by Eric Arnold (714) 447-2565
Weights above 1 milligram rounded to the nearest mg. Values less than 1 milligram given in scientific notation.

Sub-component	Material	% of total mass	Substance name	CAS #	Substance Weight (grams)	Special classification
Die	substrate	3.41%	Si	7440-21-3	0.003	
		insignificant	SiO2, amorphous	7631-86-9	trace	
	nichrome resistor	0.0003%	NiCrOx	mix of 7440-02-0, 7440-47-3, & 1308-38-9	2.15E-07	
	titanium-tungsten layer	insignificant	TiW (10/90)	mix of 7440-32-6 & 7440-33-7	trace	
	gold conductor	0.01%	Au	7440-57-5	7.25E-06	
	BCB passivation	0.01%	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	6.88E-06	
Leadframe	copper alloy	38.1%	Cu	7440-50-8	0.028	
			Fe	7439-89-6	0.001	
			P	7723-14-0	8.56E-06	
			Zn	7440-66-6	3.42E-05	
	matte Sn plating	0.84%	Sn	7440-31-5	6.30E-04	
	silver plating	0.98%	Ag	7440-22-4	7.30E-04	
Die adhesive	conductive epoxy	0.91%	Ag	7440-22-4	5.46E-04	
			trade secret	unknown	1.36E-04	non-hazardous
Wire bonds	gold	0.09%	Au	7440-57-5	6.68E-05	
Molding compound	filled epoxy	55.60%	carbon black	1333-86-4	2.08E-04	
			epoxy resin, cresol novolac	29690-82-2	8.32E-04	
			SiO2, fused silica	60676-86-0	0.036	
			trade secret	unknown	0.004	non-hazardous
Ink marking	epoxy	0.04%	trade secret	unknown	3.30E-05	non-hazardous